

120V N-Ch Power MOSFET
Feature

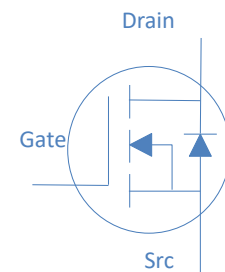
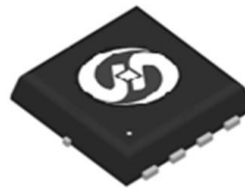
- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Body diode dv/dt capability
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

V_{DS}		120	V
$R_{DS(on),typ}$	$V_{GS}=10V$	20	m Ω
$R_{DS(on),typ}$	$V_{GS}=4.5V$	25	m Ω
I_D (Silicon Limited)		29	A
I_D (Package Limited)		26	A

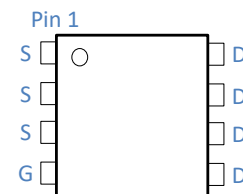
Application

- ◇ Synchronous Rectification in SMPS
- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial

DFN3.3*3.3



Part Number	Package	Marking
HGM210N12SL	DFN 3.3*3.3	GM210N12SL


Absolute Maximum Ratings at $T_J=25^{\circ}C$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^{\circ}C$	29	A
		$T_C=100^{\circ}C$	18	
		$T_C=25^{\circ}C$	26	
Continuous Drain Current (Package Limited)		$T_C=25^{\circ}C$	26	
Drain to Source Voltage	V_{DS}	-	120	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	80	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.1mH, T_C=25^{\circ}C$	5	mJ
Power Dissipation	P_D	$T_C=25^{\circ}C$	40	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	$^{\circ}C$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	65	$^{\circ}C/W$
Thermal Resistance Junction-Case	$R_{\theta JC}$	3.1	$^{\circ}C/W$

Electrical Characteristics at $T_j=25^\circ\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=250\mu A$	120	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.4	2.0	2.4	
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=120V, T_j=25^\circ\text{C}$	-	-	1	μA
		$V_{GS}=0V, V_{DS}=120V, T_j=100^\circ\text{C}$	-	-	100	
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=10V, I_D=5A$	-	20	25	$m\Omega$
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=4.5V, I_D=5A$	-	25	31	$m\Omega$
Transconductance	g_{fs}	$V_{DS}=5V, I_D=5A$	-	20	-	S
Gate Resistance	R_G	$V_{GS}=0V, V_{DS}$ Open, $f=1\text{MHz}$	-	8.5	-	Ω

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=60V, f=1\text{MHz}$	-	977	-	pF
Output Capacitance	C_{oss}		-	143	-	
Reverse Transfer Capacitance	C_{rss}		-	6.2	-	
Total Gate Charge	$Q_g(10V)$	$V_{DD}=60V, I_D=5A, V_{GS}=10V$	-	13.5	-	nC
Total Gate Charge	$Q_g(4.5V)$		-	7.6	-	
Gate to Source Charge	Q_{gs}		-	2.8	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	2.0	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=60V, I_D=5A, V_{GS}=10V,$ $R_G=10\Omega,$	-	8	-	ns
Rise time	t_r		-	8	-	
Turn off Delay Time	$t_{d(off)}$		-	14	-	
Fall Time	t_f		-	9	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=20A$	-	0.9	1.2	V
Reverse Recovery Time	t_{rr}	$V_R=60V, I_F=5A, dI_F/dt=500A/\mu s$	-	25	-	ns
Reverse Recovery Charge	Q_{rr}		-	91	-	nC

Fig 1. Typical Output Characteristics

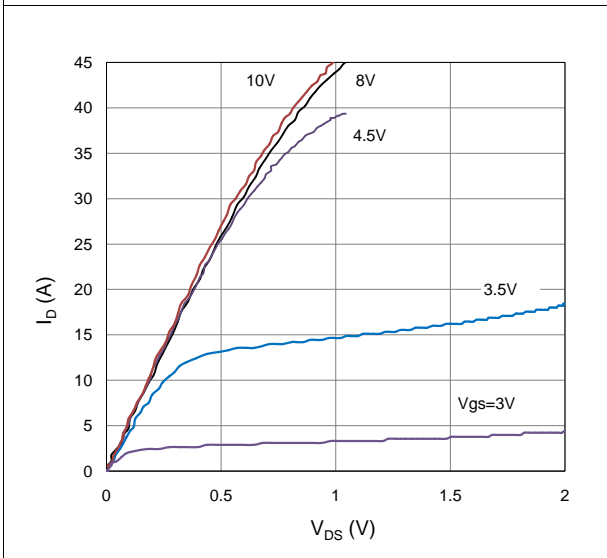


Figure 2. On-Resistance vs. Gate-Source Voltage

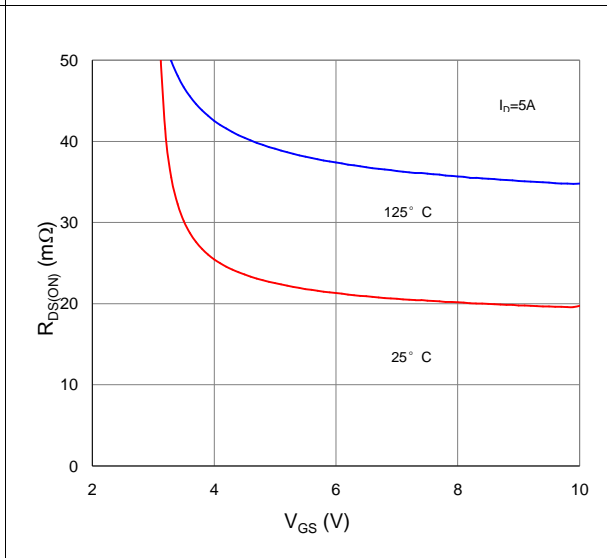


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

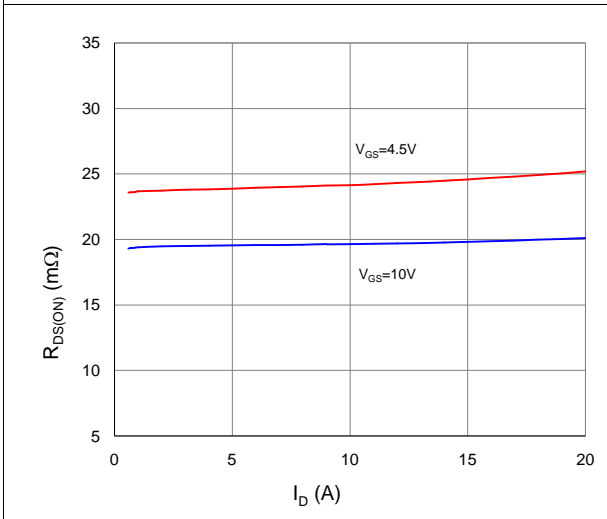


Figure 4. Normalized On-Resistance vs. Junction Temperature

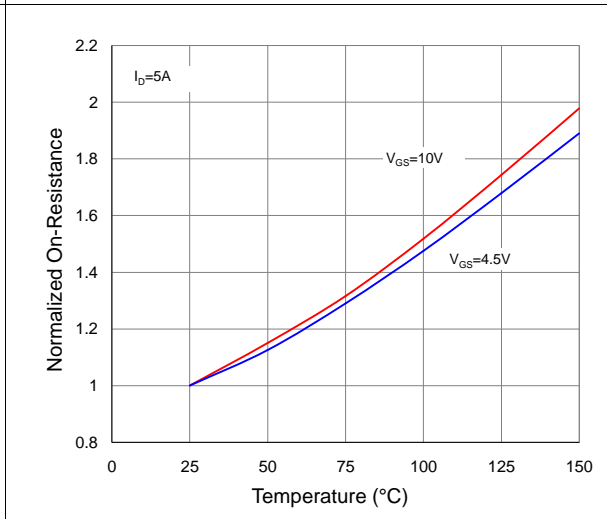


Figure 5. Typical Transfer Characteristics

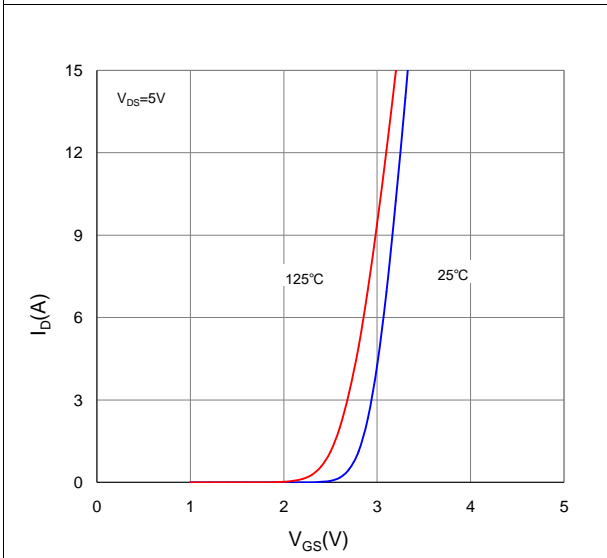


Figure 6. Typical Source-Drain Diode Forward Voltage

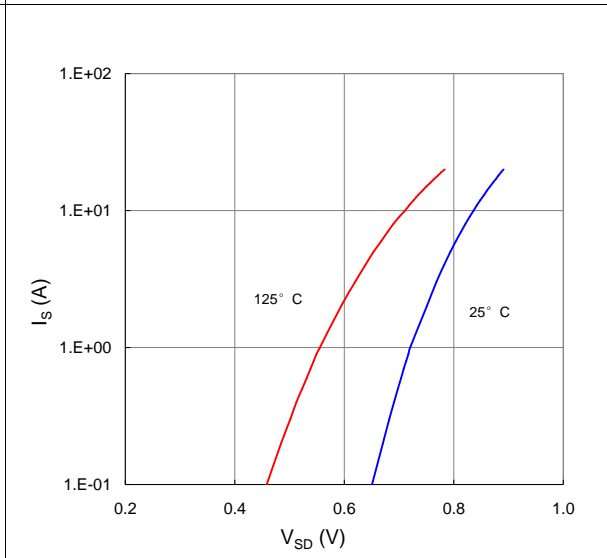


Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

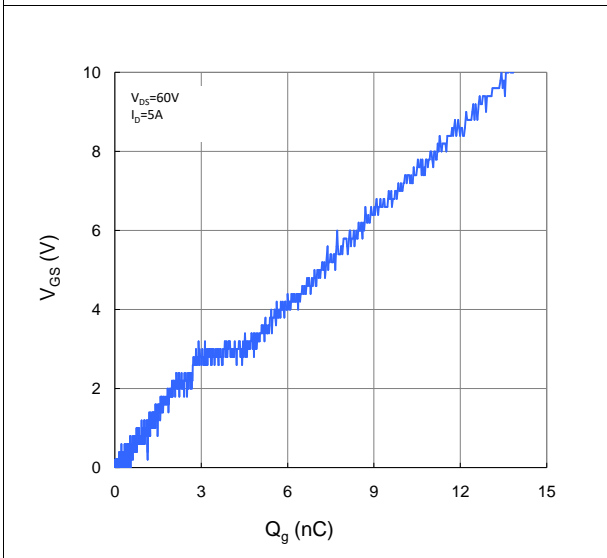


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

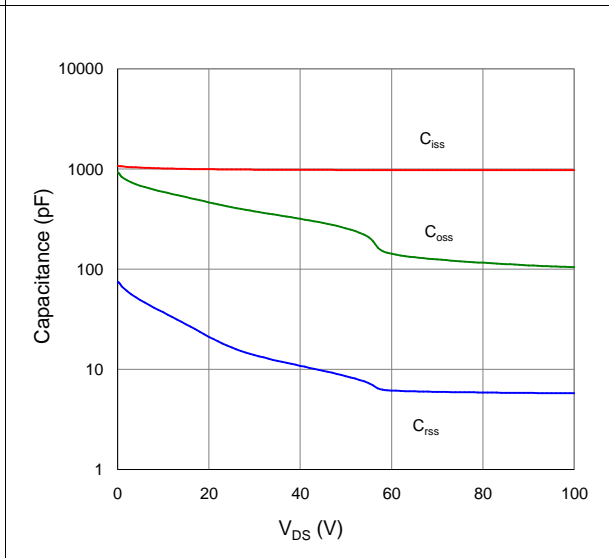


Figure 9. Maximum Safe Operating Area

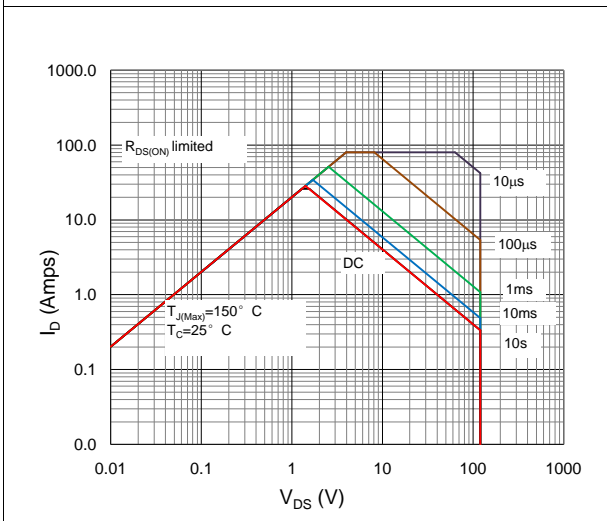


Figure 10. Maximum Drain Current vs. Case Temperature

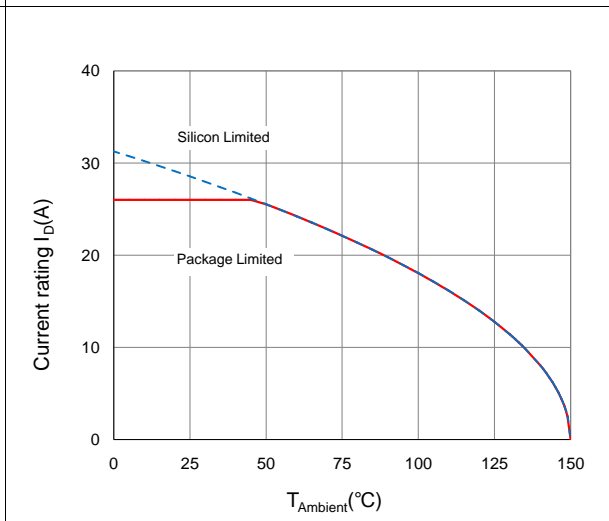
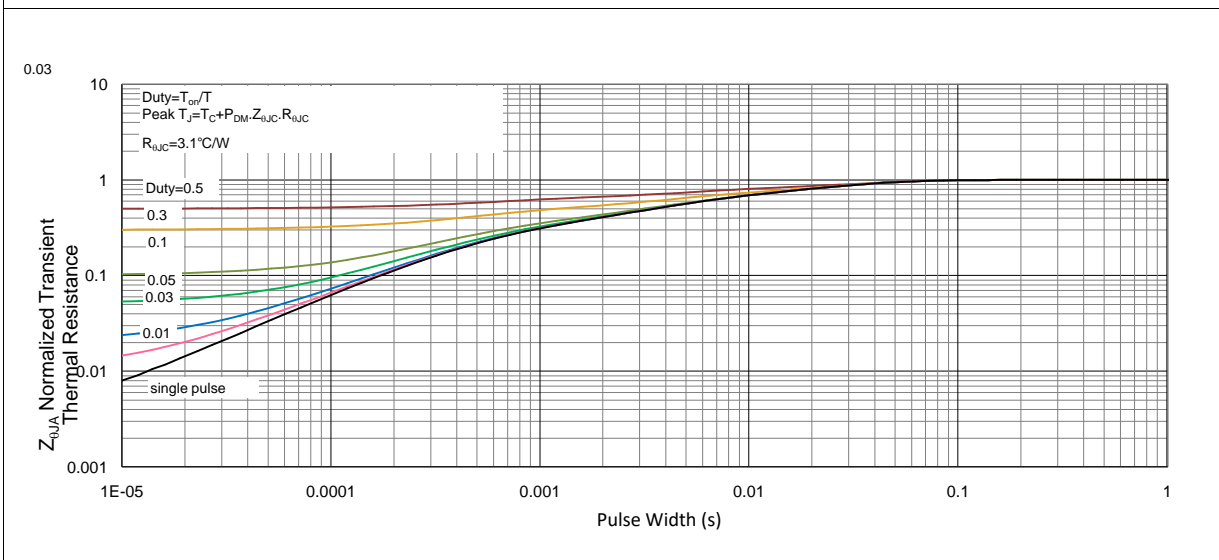
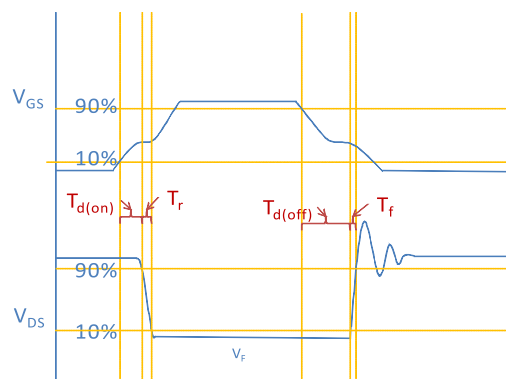
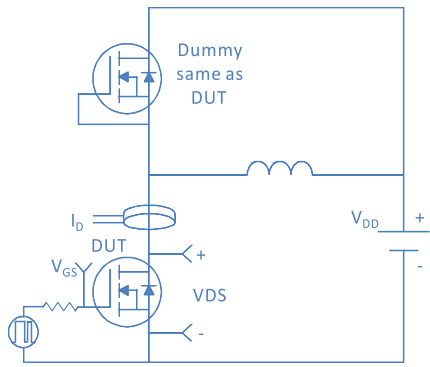


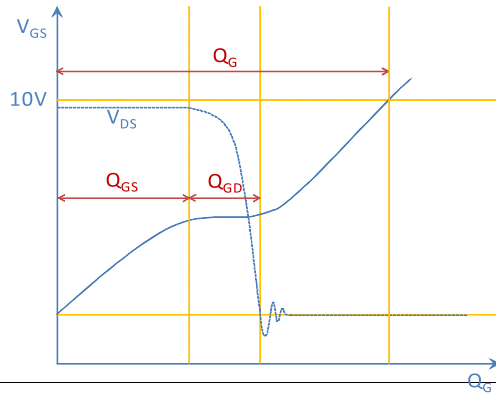
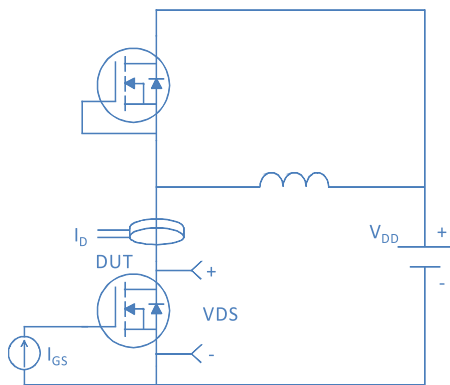
Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient



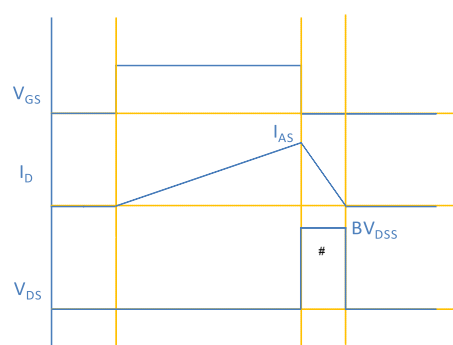
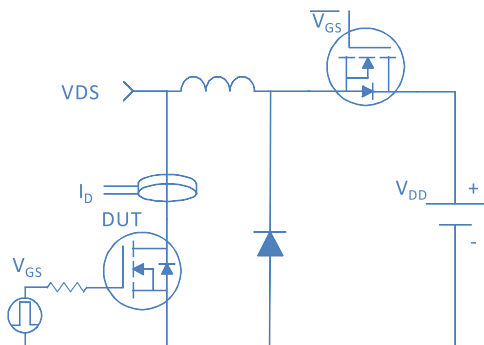
Inductive switching Test



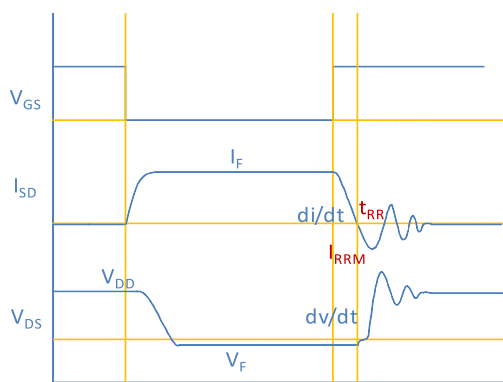
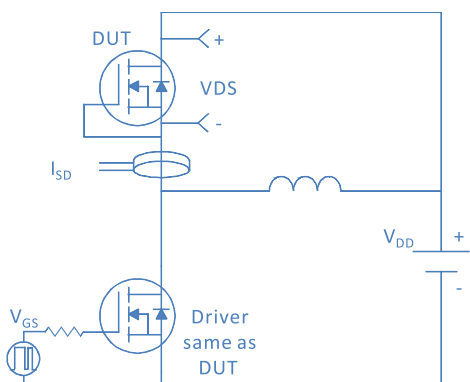
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

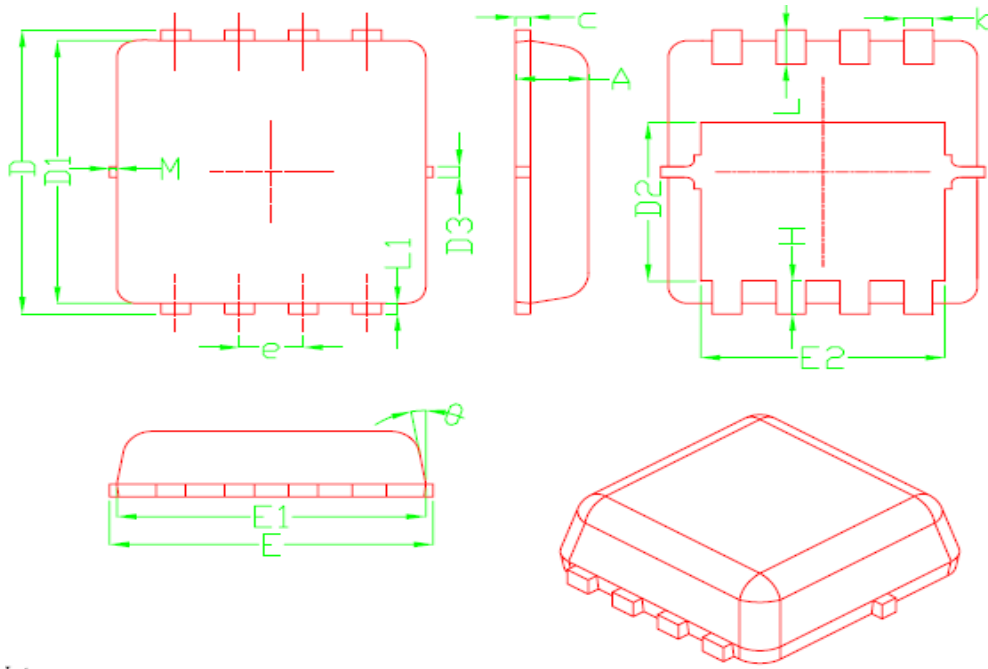


Diode Recovery Test



Package Outline

DFN3.3*3.3_P, 8 leads



SYMBOL	DIMENSIONAL REOMTS		
	MIN	NOM	MAX
A	0.70	0.75	0.80
b	0.25	0.30	0.35
c	0.10	0.15	0.25
D	3.25	3.35	3.45
D1	3.00	3.10	3.20
D2	1.78	1.88	1.98
D3	---	0.13	---
E	3.20	3.30	3.40
E1	3.00	3.15	3.20
E2	2.39	2.49	2.59
e	0.65BSC		
H	0.30	0.39	0.50
L	0.30	0.40	0.50
L1	---	0.13	---
θ	---	10°	12°
M	*	*	0.15

* Not specified